**AEC-Q101 Qualified** 

# 2.5V Drive Pch MOSFET RTL020P02FRA

### Structure

Silicon P-channel MOSFET

### Features

- 1) Low on-resistance. (180m $\Omega$  at 2.5V)
- 2) High power package.
- 3) High speed switching.
- 4) Low voltage drive. (2.5V)

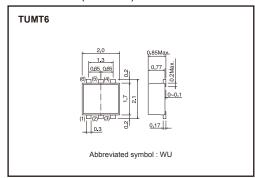
### Applications

DC-DC converter

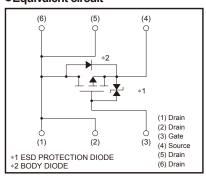
### Packaging specifications

|            | Package                      | Taping |
|------------|------------------------------|--------|
| Type       | Code                         | TR     |
|            | Basic ordering unit (pieces) | 3000   |
| RTL020P02I | 0                            |        |

### ●Dimensions (Unit: mm)



### ●Equivalent circuit



### ● Absolute maximum ratings (Ta=25°C)

| Parameter                   | Symbol           |                  | Limits      | Unit |   |  |  |  |
|-----------------------------|------------------|------------------|-------------|------|---|--|--|--|
| Drain-source voltage        |                  | V <sub>DSS</sub> |             | -20  | V |  |  |  |
| Gate-source voltage         | V <sub>GSS</sub> |                  | ±12         | V    |   |  |  |  |
| Drain augrant               | Continuous       | I <sub>D</sub>   |             | ±2   | Α |  |  |  |
| Drain current               | Pulsed           | I <sub>DP</sub>  | *1          | ±8   | Α |  |  |  |
| Source current              | Continuous       | Is               |             | -0.8 | Α |  |  |  |
| (Body diode)                | Pulsed           | I <sub>SP</sub>  | *1          | -8   | Α |  |  |  |
| Total power dissipation     | PD               | *2               | 1           | W    |   |  |  |  |
| Channel temperature         | Tch              |                  | 150         | °C   |   |  |  |  |
| Range of Storage temperatur | Tstg             |                  | -55 to +150 | °C   |   |  |  |  |

<sup>\*1</sup> Pw≤10µs, Duty cycle≤1% \*2 Mounted on a ceramic board

### \*2 Wounted on a ceramic board

### Thermal resistance

| Parameter          | Symbol      | Limits | Unit   |  |
|--------------------|-------------|--------|--------|--|
| Channel to ambient | Rth(ch-a) * | 125    | °C / W |  |

<sup>\*</sup> Mounted on a ceramic board.

# ●Electrical characteristics (Ta=25°C)

| Parameter                               | Symbol                | Min. | Тур. | Max. | Unit | Conditions                                    |  |
|---|-----------------------|------|------|------|------|---|--|
| Gate-source leakage                     | I <sub>GSS</sub>      | _    | -    | ±10  | μΑ   | V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V    |  |
| Drain-source breakdown voltage          | V <sub>(BR) DSS</sub> | -20  | _    | _    | V    | I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V    |  |
| Zero gate voltage drain current         | I <sub>DSS</sub>      | _    | -    | -1   | μΑ   | V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V   |  |
| Gate threshold voltage                  | VGS (th)              | -0.7 | -    | -2.0 | V    | V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA |  |
| Olelia desirente de la constanta        | *                     | _    | 100  | 135  | mΩ   | I <sub>D</sub> = -2A, V <sub>G</sub> S= -4.5V |  |
| Static drain-source on-state resistance | R <sub>DS (on)</sub>  | _    | 110  | 150  | mΩ   | I <sub>D</sub> = -2A, V <sub>GS</sub> = -4V   |  |
| resistance                              |                       | -    | 180  | 250  | mΩ   | I <sub>D</sub> = -1A, V <sub>GS</sub> = -2.5V |  |
| Forward transfer admittance             | Y <sub>fs</sub>   *   | 1.2  | ı    | _    | S    | V <sub>DS</sub> = -10V, I <sub>D</sub> = -1A  |  |
| Input capacitance                       | Ciss                  | _    | 430  | -    | pF   | V <sub>DS</sub> = -10V                        |  |
| Output capacitance                      | Coss                  | _    | 80   | _    | pF   | V <sub>GS</sub> =0V                           |  |
| Reverse transfer capacitance            | Crss                  | _    | 55   | _    | pF   | f=1MHz  |  |
| Turn-on delay time                      | t <sub>d (on)</sub> * | _    | 11   | _    | ns   | ID= -1A                                       |  |
| Rise time                               | tr *                  | _    | 13   | _    | ns   | VDD≒ −15V<br>VGS= −4.5V<br>RL=15Ω<br>RG=10Ω   |  |
| Turn-off delay time                     | td (off) *            | _    | 38   | _    | ns   |   |  |
| Fall time                               | t <sub>f</sub> *      | _    | 12   | _    | ns   |   |  |
| Total gate charge                       | Qg *                  | _    | 4.9  | _    | nC   | V <sub>DD</sub> ≒−15V R <sub>L</sub> =7.5Ω    |  |
| Gate-source charge                      | Q <sub>gs</sub> *     | _    | 1.2  | -    | nC   | $V_{GS}$ = -4.5V R <sub>G</sub> =10 $\Omega$  |  |
| Gate-drain charge                       | Q <sub>gd</sub> *     | _    | 1.3  | _    | nC   | I <sub>D</sub> = -2A                          |  |

<sup>\*</sup>Pulsed

# ●Body diode characteristics (Source-drain) (Ta=25°C)

| Parameter       | Symbol | Min. | Тур. | Max. | Unit | Conditions                     |
|-----------------|--------|------|------|------|------|--------------------------------|
| Forward voltage | VsD    | _    | _    | -1.2 | V    | Is= -0.8A, V <sub>GS</sub> =0V |

### Electrical characteristic curves

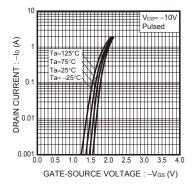


Fig.1 Typical Transfer Characteristics

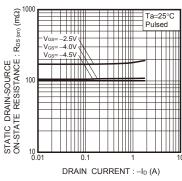


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

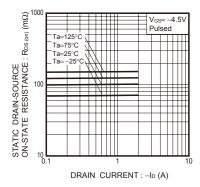


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

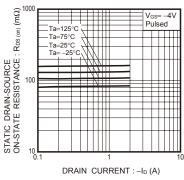


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

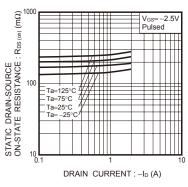


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

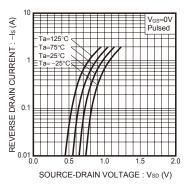


Fig.6 Reverse Drain Current vs. Source-Drain Voltage

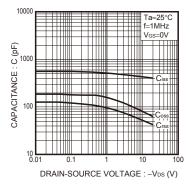


Fig.7 Typical Capacitance vs. Drain-Source Voltage

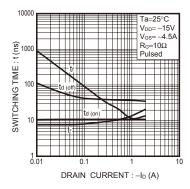


Fig.8 Switching Characteristics

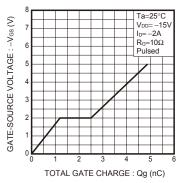


Fig.9 Dynamic Input Characteristics

### Measurement circuits

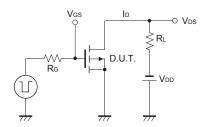


Fig.10 Switching Time Measurement Circuit

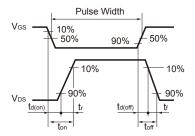


Fig.11 Switching Waveforms

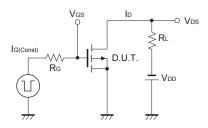


Fig.12 Gate Charge Measurement Circuit

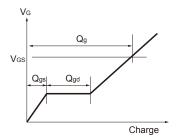


Fig.13 Gate Charge Waveforms

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|---------|----------|------------|---------|
| CLASSⅢ  | CLACCIII | CLASS II b | СГУССШ  |
| CLASSIV | CLASSⅢ   | CLASSⅢ     | CLASSII |

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